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(54) **PLANARIZATION TREATMENT OF
PRESSURE SENSITIVE ADHESIVE FOR
RIGID-TO-RIGID SUBSTRATE LAMINATION**

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See application file for complete search history.

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(57) **ABSTRACT**

The present invention is a process for performing a planarization treatment of pressure-sensitive adhesive (PSA). The process includes positioning a first substrate onto a support surface of a planarization tool. The process further includes placing at least one layer of PSA onto the first substrate. The process further includes positioning a second substrate onto the layer(s) of PSA. The process further includes applying a pressure to the second substrate via a flexible membrane, said pressure being applied in a generally uniform, unidirectional and localized manner. Further, the applied pressure flattens the PSA between the first

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